

# GSMDS4910

## 40V N-Channel MOSFETs

### Product Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

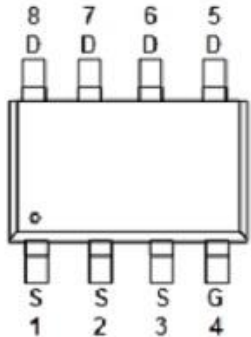
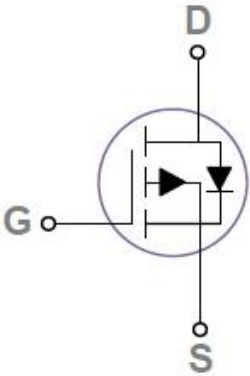
### Features

- 40V, 6.7A,  $R_{DS(ON)}=19m\Omega@V_{GS}=-10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- SOP-8 package design

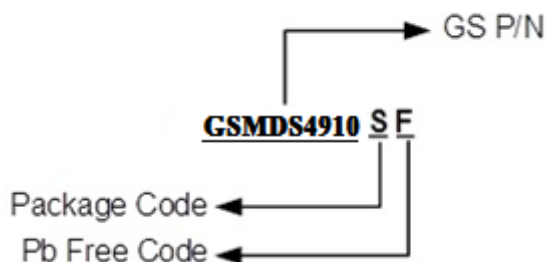
### Applications

- Notebook
- Load Switch
- LED applications
- Hand-Held Device

### Packages & Pin Assignments

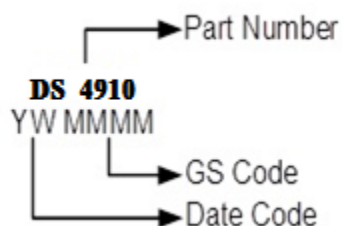
GSMDS4910SF(SOP-8)			
			
			
Pin	Description	Pin	Description
1	Source	5	Drain
2	Source	6	Drain
3	Source	7	Drain
4	Gate	8	Drain

## Ordering Information



Part Number	Package	Quantity/Reel
GSMDS4910SF	SOP-8	4000 PCS

## Marking Information



## Absolute Maximum Ratings

T<sub>A</sub>=25°C Unless otherwise noted

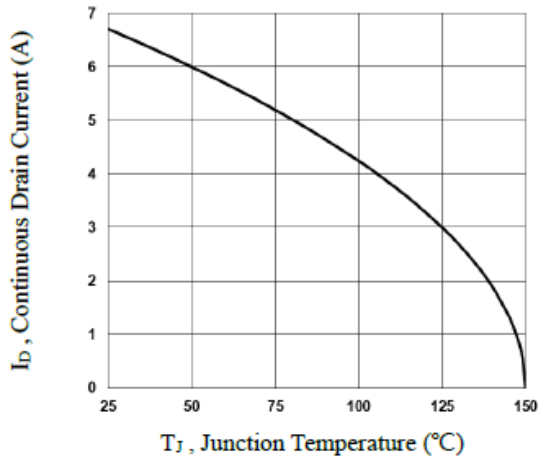
Symbol	Parameter	Typical	Unit
V <sub>DS</sub>	Drain-Source Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current	T <sub>A</sub> =25°C	6.7
		T <sub>A</sub> =100°C	5.4
I <sub>DM</sub>	Pulsed Drain Current	26.8	A
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> =25°C)	1.47	W
	Power Dissipation (Derate above 25°C)	0.12	W/°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient	85	°C/W

## Electrical Characteristics

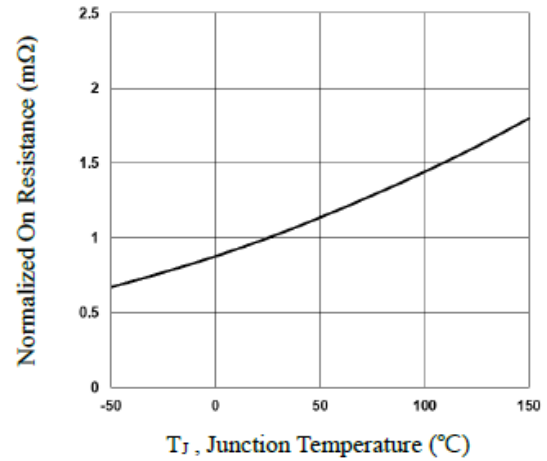
T<sub>A</sub>=25°C Unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	40			V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA		0.034		V/°C
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.2	1.5	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA		-4.3		mV/°C
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V			1	uA
		V <sub>DS</sub> =32V, V <sub>GS</sub> =0V, T <sub>J</sub> =85°C			10	
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current			6.7	A
I <sub>SM</sub>	Pulsed Source Current				13.4	
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =6A		16	19	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A		20	125	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =3A		6		S
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A			1	V
<b>Dynamic</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =32V, V <sub>GS</sub> =10V, I <sub>D</sub> =6A		11.8	23	nC
Q <sub>gs</sub>	Gate-Source Charge			1.7	3.4	
Q <sub>gd</sub>	Gate-Drain Charge			4	8	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, F=1MHz		722	1440	pF
C <sub>oss</sub>	Output Capacitance			83	166	
C <sub>rss</sub>	Reverse Transfer Capacitance			61	122	
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =20V, I <sub>D</sub> =1A, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω		5	10	ns
t <sub>r</sub>				8	16	
t <sub>d(off)</sub>	Turn-Off Time			17	34	
t <sub>f</sub>				5	10	

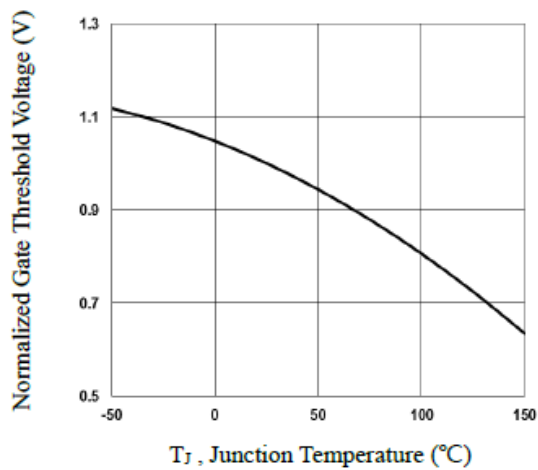
## Typical Performance Characteristics



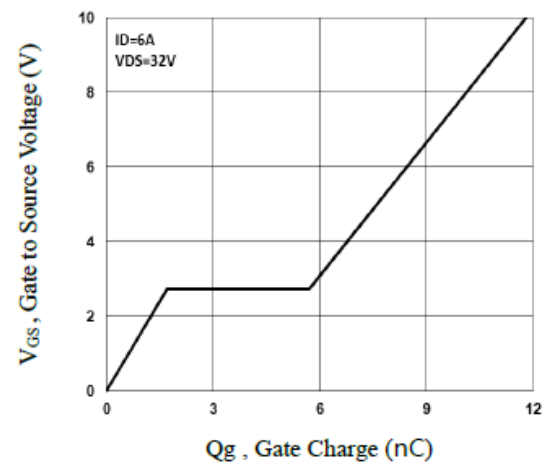
**Fig.1 Continuous Drain Current vs.  $T_J$**



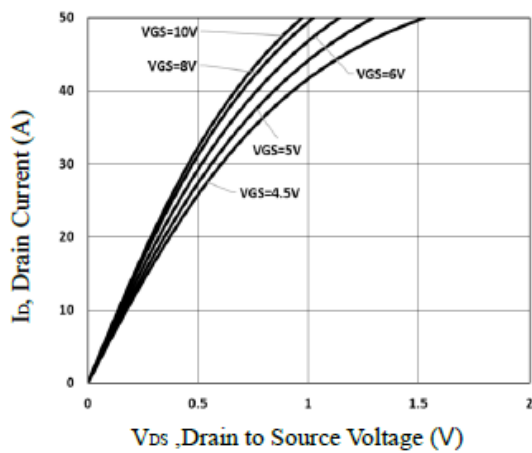
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



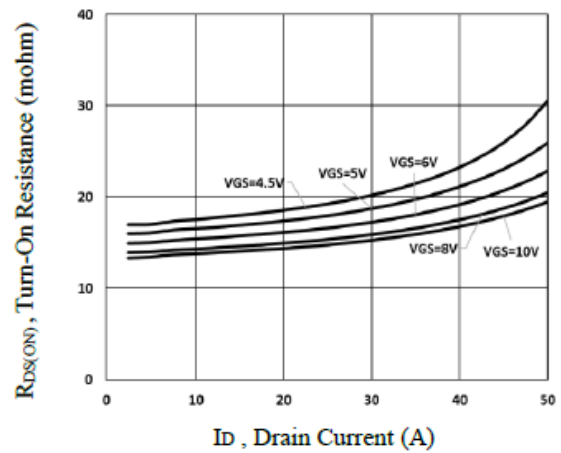
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



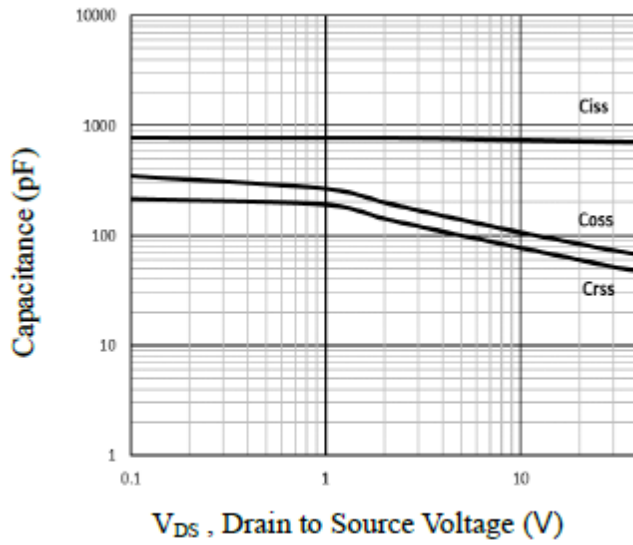
**Fig.4 Gate Charge Waveform**



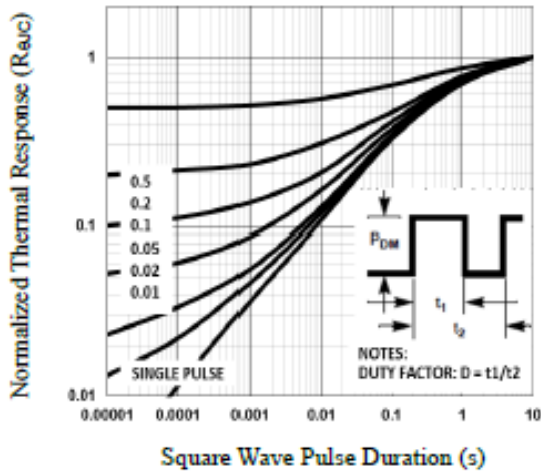
**Fig.5 Typical Output Characteristics**



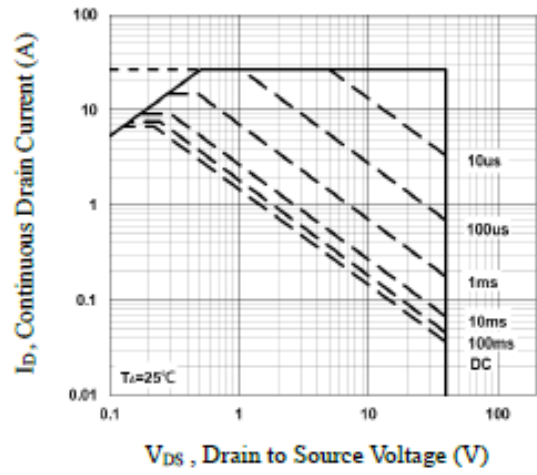
**Fig.6 Turn-On Resistance vs.  $I_D$**



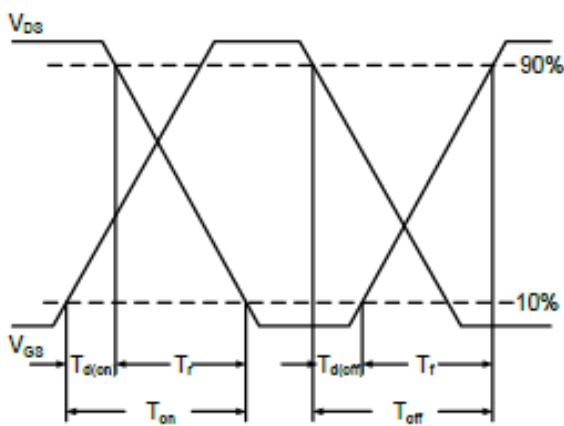
**Fig.7 Capacitance Characteristics**



**Fig.8 Normalized Transient Impedance**

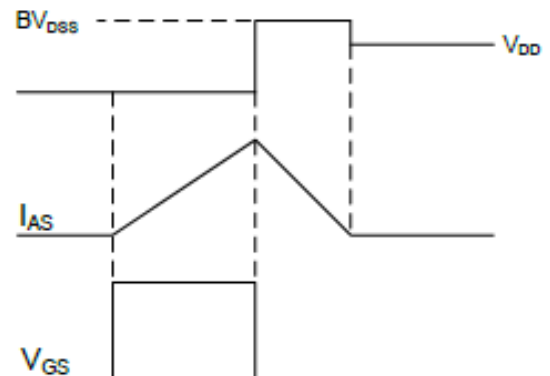


**Fig.9 Maximum Safe Operation Area**



**Fig.10 Switching Time Waveform**

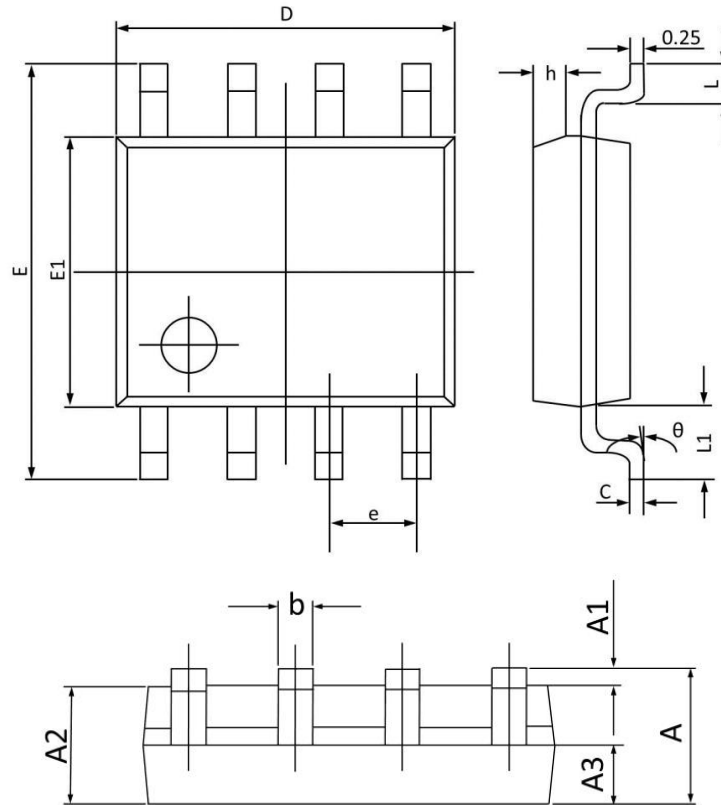
$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$



**Fig.11 EAS Waveform**

Package Dimension

## SOP-8 PACKAGE









Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.068
A1	0.100	0.250	0.004	0.009
A2	1.300	1.500	0.052	0.059
A3	0.600	0.700	0.024	0.027
b	0.390	0.480	0.016	0.018
c	0.210	0.260	0.009	0.010
D	4.700	5.100	0.186	0.200
E	5.800	6.200	0.229	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.500	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°

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